

规格书编号

**SPEC NO:** 

# 产品规格书 SPECIFICATION

CUSTOMER 客户:							
PRODUCT 产品:	SAW FILTER						
MODEL NO 型 号:	HDF328A-F11						
PREPARED 编 制:	CHECKED 审 相	<b>蒸:</b>					
APPROVED 批准:	<b>DATE</b> 日 其	月:2006-5-11					
客户确认 CUSTOMER RECEIVED:							
审核 CHECKED	批准 APPROVED	日期 DATE					

# 无锡市好达电子有限公司 Shoulder Electronics Limited



# 更改历史记录 History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark



# 1. SCOPE

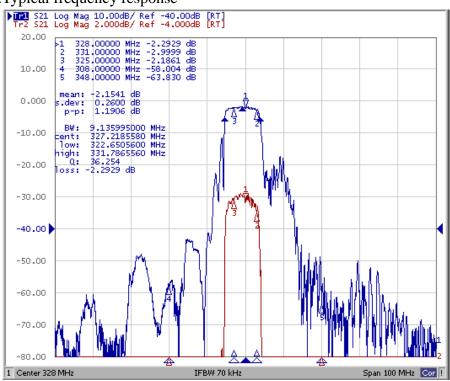
This specification shall cover the characteristics of SAW filter With HDF328A used for the page system.

# 2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V	
AC Voltage Vpp	10V50Hz/60Hz	
Operation temperature	-40°C to +85°C	
Storage temperature	-45°C to +85°C	
RF Power Dissipation	0dBm	

**Electronic Characteristics** 

#### 2-1. Typical frequency response

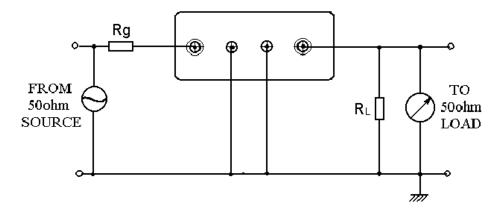


### 2-2. Electrical characteristics

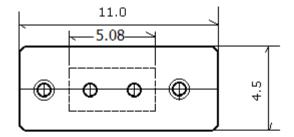
Part number	HDF328A	Unit
Nominal center frequency (Fo)	328	MHz
Insertion Loss		
1.Fo -45.8MHz to Fo -39.8MHz	45min.	dB
$2.\text{Fo}\pm3\text{MHz}$	4.5max.	
3.Fo +39.5MHz to Fo +45.8MHz	45min.	
Ripple (with Fo ±3MHz)	2.0max	dB
Input/Output Impedance(Nominal)	50/0	Ω //pF

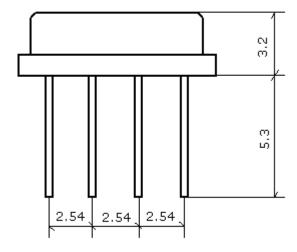
SAW FILTER HDF328A- F11

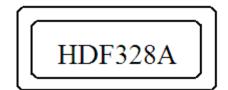
# 2. TEST CIRCUIT



# 4. DIMENSION









**SAW FILTER** 

## 5. ENVIRONMENTAL CHARACTERISTICS

#### 5-1 Temperature cycling

Subject the device to a low temperature of  $-40^{\circ}$ C for 30 minutes. Following by a high temperature of  $+25^{\circ}$ C for 5 Minutes and a higher temperature of  $+85^{\circ}$ C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2-2.

#### 5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at  $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for  $10\pm 1$  sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2-2.

#### 5-3 Solderability

Submerge the device terminals into the solder bath at  $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$  for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2-2.

#### 5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2-2.

#### 5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2-2.

#### 6. REMARK

#### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

#### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

#### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.